

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	6	"stress releasing slit" or (stress-releasing adj slit)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/24 13:41
2	BRS	L2	320325	slit or slits	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/24 13:41
3	BRS	L3	131874	(reduc\$6 or less\$6 or avoid\$4) near4 (warp\$6 or bent or bend\$4 or stress)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/24 13:42
4	BRS	L4	1024	2 same 3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/24 13:43
5	BRS	L5	370	2 near8 3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/24 13:43

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	18	5 and (LCD or "liquid crystal")	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/24 13:43

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L5	117449 6	slit\$4 or gap\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/22 18:22
2	BRS	L6	70948	<i>blend \$4</i> (flex\$6 or fold\$4) near4 (substrate or board or PCB or CB)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/22 18:22
3	BRS	L7	716657 2	bridg\$4 or connect\$4 or link\$4 or tie or crossing or span\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/22 18:23
4	BRS	L8	1107	5 same 6 same 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/22 18:25
5	BRS	L9	1077	5 near8 6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/22 18:25

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L10	378	9 same 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/22 18:26

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	117569 2	slit\$4 or gap\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/26 19:00
2	BRS	L2	87193	(flex\$6 or fold\$4 or bend\$4 or bent\$4) near4 (substrate or board or PCB or CB)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/26 19:00
3	BRS	L3	717823 4	bridg\$4 or connect\$4 or link\$4 or tie or crossing or span\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/26 19:01
4	BRS	L4	298	1 near8 2 near16 3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/01/26 19:02

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L4	804	(stress or flex\$4 or strain or bend\$4 or bent or pressure) near4 releas\$4 same slit\$3	USPAT	2004/02/20 18:39
2	BRS	L6	1001	stress near4 slit\$4	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 18:38
3	BRS	L5	39	(stress near2 releas\$6) near4 slit\$2	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 18:38
4	BRS	L7	16	(stress near4 slit\$4) and (tape near2 carrier)	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 18:38
5	BRS	L9	1249	(stress or flex\$4 or strain or bend\$4 or bent or pressure) near4 releas\$4 same slit\$3	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 19:18

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L10	53328	TFT or "thin film transistor"	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 18:40
7	BRS	L12	48378	(flex\$6 near2 (substrate\$3 or wafer\$3 or board\$3))	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 18:41
8	BRS	L13	28	9 and 12	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 18:41
9	BRS	L14	18321	(second! or another or addition\$6) near4 slit\$3	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 19:19
10	BRS	L15	163	9 and 14	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/20 19:19